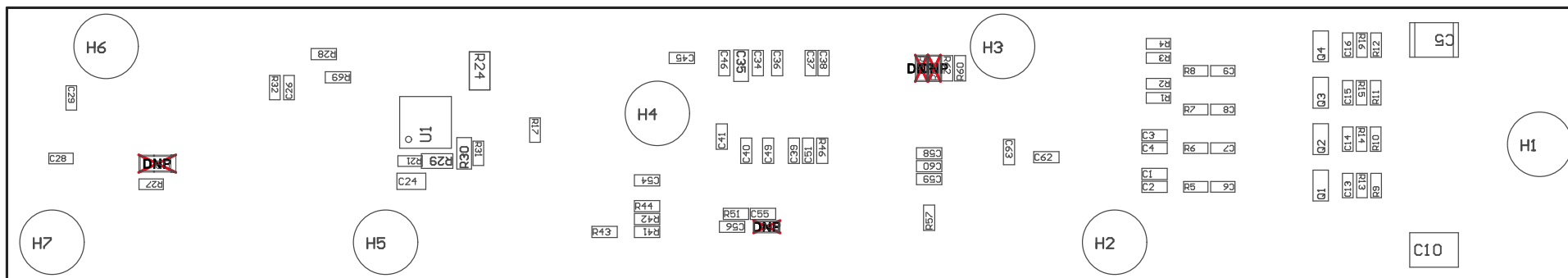


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01463	REV: A	SVN REV: Not In VersionControl
	TID #: TIDA-01463		
PLOT NAME = Top Assembly Drawing	GENERATED : 11/2/2017 2:00:16 PM		TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01463	REV: A	SVN REV: Not In VersionControl
	TID #: TIDA-01463		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 11/2/2017	2:00:18 PM	TEXAS INSTRUMENTS

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